

**AMENDMENTS TO THE SPECIFICATION:**

**Please amend the paragraph beginning on page 1, line 17, as follows:**

Figs. 8 to 11 show the structure of a conventional ceramic package. Referring to Fig. 8, a ceramic package 1 is comprised of a cavity 3 where a semiconductor element 2 is to be mounted, and a feed-through 4 for connecting the inside and outside of the cavity 3. As shown in Figs. 9 and 10, the feed-through 4 is divided into a coplanar line 4a and inner layer line 4b, and is comprised of a signal conductor 5, a ground conductor 6a on the lower surface of a first layer substrate 1a, a ground conductor 6b of the coplanar line 4a, and a ground conductor 6c on the upper surface of a second layer substrate 1b (see Fig. 9).

**Please amend the paragraph beginning on page 2, line 2, as follows:**

The cavity 3 is hermetically sealed by an upper lid 7 so that it is hermetically held (see Fig. 8). In order to equalize electric potential, a plurality of via holes 8a for connecting the ground conductors 6a and ground conductor 6b to each other, and a plurality of via holes 8b for connecting the ground conductors 6a, 6b, and 6c to each other are formed along the signal propagating direction (see Fig. 9).

**Please amend, for a second time, the replacement paragraph beginning on page 2, line 10, as follows:**

As shown in Figs. 10 and 11, in the structure of the conventional ceramic package, when a distance  $\lambda$  from a connection interface c-c' (see Fig. 10) between the coplanar line 4a and inner layer line 4b to the center of the endmost via hole 8b formed to extend through the first and second layer substrates 1a and 1b (see Fig. 11) increases with respect to a signal wavelength, a signal is radiated in an outward propagation mode between the connection interface c-c' and the endmost via hole 8b into a plane-parallel plate, constituted by the ground conductor 6b of the coplanar line 4a and the ground conductor 6c on the upper surface of the second layer substrate 1b. Studies made by the present inventors clarified that in the conventional ceramic package, the transmission characteristics in the feed-through 4 degraded due to this signal radiation.

**Please amend, for a second time, the paragraph beginning on page 5, line 26 as follows:**

As shown in Figs. 1, 2 and 3, the feed-through 104 (see Fig. 1) is comprised of a coplanar line 104a formed on the first layer substrate 101a, and an inner layer line 104b obtained by forming the second layer substrate 101b on the coplanar line 104a. More specifically, the inner layer line 104b is comprised of the coplanar line 104a formed between the first and second layer substrates 101a and 101b (see Fig. 2). The feed-through 104 has a conductor structure consisting of a signal conductor (strip conductor) 105 formed on the upper surface of the first layer substrate 101a, a ground conductor 106a formed on the lower surface of the first layer substrate 101a, a pair of ground conductors (planar ground conductors) 106b formed on two sides of the signal conductor 105 at a predetermined gap, and a ground conductor 106c formed on the upper surface of the second layer substrate 101b, as shown in Fig. 2. The cavity 103 is hermetically sealed by an upper lid 107 so that it is hermetically held, as shown in Fig. 1.

**Please amend the paragraph beginning on page 9, line 7, as follows:**

If the frequency is high, a higher-order mode exists which propagates through a waveguide structure constituted by the via holes 108b and ground conductors 106a, 106b, and 106c. Therefore, the signal mode is transformed into the higher-order mode due to the discontinuity at the connection interface a-a' between the coplanar line 104a and inner layer line 104b, thereby degrading the transmission characteristics. In order to cut off this higher-order mode, the pitch w (see Fig. 3) of the via holes 108a and 108b in a direction perpendicular to the signal propagating direction desirably satisfies the following expression (4):

$$w < \frac{c}{2f\sqrt{\epsilon_r}} \quad \dots (4)$$

**Please amend the paragraph beginning on page 11, line 7, as follows:**

The difference between the first and second embodiments resides in that, in the second embodiment, as shown in Fig. 5, on a connection interface b-b' between a coplanar line 104a and inner layer line 104b (see Fig. 6), a pair of plate-like interface metal portions 110 are formed by plating or the like on the two sides of a signal conductor 105 so as to connect ground conductors 106b and 106c to each other. In this case, as shown in Fig. 6, the interface metal portions 110 project toward the coplanar line 104a by an amount corresponding to the thicknesses of the plates.

**AMENDMENTS TO THE DRAWINGS:**

Replacement drawing sheet 1, which is a second replacement sheet having been amended once previously, and replacement sheet 2 are attached to this Response as an Appendix. These replacement sheets contain revisions to Figures 2 and 3 in which the reference numeral "104" has been added to each figure according to the guidelines set forth in the Office Action. Applicants respectfully submit that no new matter is added by these amendments.